

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Huang, *et al.*

Docket No.: TSM03-0340

Serial No.: 10/706,156

Art Unit: 2821

Filed: November 12, 2003

Examiner: Tai-Chun Huang

For: Integration Film Scheme for Copper/Low-k Interconnect

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

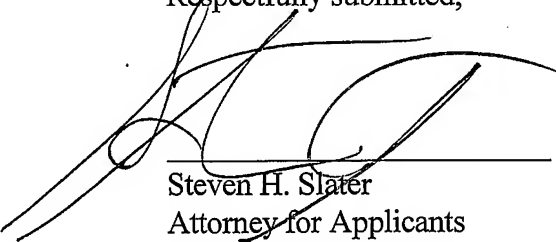
COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

In response to the Notice of Allowance, and more particularly to the Examiner's statement of reasons for allowance, Applicants respectfully submit the following remarks.

In the Notice of Allowance, Examiner asserted that "the dielectric constant that is less than that of SiO₂, is understood to be limited to the dielectric constant range disclosed in the specification." In response, Applicants readily agree that an exemplary dielectric constant range is disclosed in the specification, and further recognizes that presently preferred embodiments of the invention fall within the disclosed range. Applicants further assert, however, that the claimed invention is not so limited and nothing in the prior art of record would require interpreting the claim language in so limited a fashion. Hence, Applicants traverse the assertion.

Respectfully submitted,

11 JUNE 2007
Date


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